

## P-Channel 30-V (D-S) MOSFET

### PRODUCT SUMMARY

| $V_{DS}$ (V) | $R_{DS(on)}$ ( $\Omega$ )    | $I_D$ (A) <sup>d</sup> | $Q_g$ (Typ.) |
|--------------|------------------------------|------------------------|--------------|
| - 30         | 0.0125 at $V_{GS} = - 10$ V  | - 11.6                 | 22 nC        |
|              | 0.0180 at $V_{GS} = - 4.5$ V | - 10                   |              |

### FEATURES

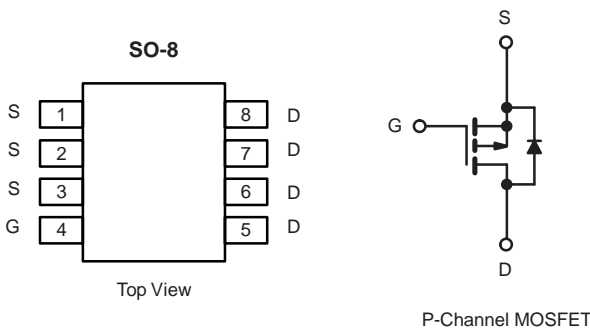
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET<sup>®</sup> Power MOSFET
- 100 %  $R_g$  Tested
- 100 % UIS Tested



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
Available

### APPLICATIONS

- Load Switches
  - Notebook PCs
  - Desktop PCs



### ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

| Parameter  | Symbol         | Limit         | Unit                  |
|--|----------------|---------------|-----------------------|
| Drain-Source Voltage                             | $V_{DS}$       | - 30          | V                     |
| Gate-Source Voltage                              | $V_{GS}$       | $\pm 20$      |                       |
| Continuous Drain Current ( $T_J = 150$ °C)       | $I_D$          | $T_C = 25$ °C | - 11.6                |
|  |                | $T_C = 70$ °C | - 10.5                |
|  |                | $T_A = 25$ °C | - 8.7 <sup>a, b</sup> |
|  |                | $T_A = 70$ °C | - 7.7 <sup>a, b</sup> |
| Pulsed Drain Current                             | $I_{DM}$       | - 40          | A                     |
| Continuous Source-Drain Diode Current            | $I_S$          | $T_C = 25$ °C | - 4.6                 |
|  |                | $T_A = 25$ °C | 2.0 <sup>a, b</sup>   |
| Avalanche Current                                | $I_{AS}$       | - 20          |                       |
| Single-Pulse Avalanche Energy                    | $E_{AS}$       | 20            | mJ                    |
| Maximum Power Dissipation                        | $P_D$          | $T_C = 25$ °C | 5.6                   |
|  |                | $T_C = 70$ °C | 3.6                   |
|  |                | $T_A = 25$ °C | 2.5 <sup>a, b</sup>   |
|  |                | $T_A = 70$ °C | 1.6 <sup>a, b</sup>   |
| Operating Junction and Storage Temperature Range | $T_J, T_{stg}$ | - 55 to 150   | °C                    |

### THERMAL RESISTANCE RATINGS

| Parameter                                   | Symbol     | Typical | Maximum | Unit |
|---|------------|---------|---------|------|
| Maximum Junction-to-Ambient <sup>a, c</sup> | $R_{thJA}$ | 39      | 50      | °C/W |
| Maximum Junction-to-Foot                    | $R_{thJF}$ | 18      | 22      |      |

Notes:

- Surface mounted on 1" x 1" FR4 board.
- $t = 10$  s.
- Maximum under Steady State conditions is 85 °C/W.
- Based on  $T_C = 25$  °C.

| SPECIFICATIONS T <sub>J</sub> = 25 °C, unless otherwise noted |                                      |  |   |        |        |       |    |
|---|--------------------------------------|--|---|--------|--------|-------|----|
| Parameter   | Symbol                               | Test Conditions  | Min.  | Typ.   | Max.   | Unit  |    |
| Static  |                                      |  |   |        |        |       |    |
| Drain-Source Breakdown Voltage                                | V <sub>DS</sub>                      | V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA   | - 30  |        |        | V     |    |
| V <sub>DS</sub> Temperature Coefficient                       | ΔV <sub>DS</sub> /T <sub>J</sub>     | I <sub>D</sub> = - 250 μA  |   | - 31   |        | mV/°C |    |
| V <sub>GS(th)</sub> Temperature Coefficient                   | ΔV <sub>GS(th)</sub> /T <sub>J</sub> |  |   | 5.5    |        |       |    |
| Gate-Source Threshold Voltage                                 | V <sub>GS(th)</sub>                  | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA  | - 1.0   |        | - 3.0  | V     |    |
| Gate-Source Leakage   | I <sub>GSS</sub>                     | V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 25 V  |   |        | ± 100  | nA    |    |
| Zero Gate Voltage Drain Current                               | I <sub>DSS</sub>                     | V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V  |   |        | - 1    | μA    |    |
|   |                                      | V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C  |   |        | - 5    |       |    |
| On-State Drain Current <sup>a</sup>                           | I <sub>D(on)</sub>                   | V <sub>DS</sub> ≥ - 10 V, V <sub>GS</sub> = - 10 V   | - 30  |        |        | A     |    |
| Drain-Source On-State Resistance <sup>a</sup>                 | R <sub>DS(on)</sub>                  | V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 10 A  |   | 0.011  | 0.0125 | Ω     |    |
|   |                                      | V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 7 A  |   | 0.012  | 0.018  |       |    |
| Forward Transconductance <sup>a</sup>                         | g <sub>fs</sub>                      | V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 10 A  |   | 23     |        | S     |    |
| Dynamic <sup>b</sup>  |                                      |  |   |        |        |       |    |
| Input Capacitance   | C <sub>iss</sub>                     | V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz   |   | 1960   |        | pF    |    |
| Output Capacitance  | C <sub>oss</sub>                     |  |   | 380    |        |       |    |
| Reverse Transfer Capacitance                                  | C <sub>rss</sub>                     |  |   | 325    |        |       |    |
| Total Gate Charge   | Q <sub>g</sub>                       | V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 10 A  |   | 43     | 65     | nC    |    |
| Gate-Source Charge  | Q <sub>gs</sub>                      | V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 10 A   |   | 22     | 33     |       |    |
| Gate-Drain Charge   | Q <sub>gd</sub>                      |  |   | 6      |        |       |    |
| Gate Resistance   | R <sub>g</sub>                       |  |   | 11     |        |       |    |
| Turn-On Delay Time  | t <sub>d(on)</sub>                   | f = 1 MHz  | 0.3   | 1.3    | 2.5    | Ω     |    |
| Rise Time   | t <sub>r</sub>                       |  | V <sub>DD</sub> = - 15 V, R <sub>L</sub> = 3 Ω<br>I <sub>D</sub> ≅ - 5 A, V <sub>GEN</sub> = - 10 V, R <sub>g</sub> = 1 Ω |        | 11     | 22    | ns |
| Turn-Off DelayTime  | t <sub>d(off)</sub>                  |  |   |        | 13     | 25    |    |
| Fall Time   | t <sub>f</sub>                       |  |   |        | 32     | 50    |    |
| Turn-On Delay Time  | t <sub>d(on)</sub>                   |  |   | 9      | 18     |       |    |
| Rise Time   | t <sub>r</sub>                       | V <sub>DD</sub> = - 15 V, R <sub>L</sub> = 3 Ω<br>I <sub>D</sub> ≅ - 5 A, V <sub>GEN</sub> = - 4.5 V, R <sub>g</sub> = 1 Ω |   | 44     | 70     |       |    |
| Turn-Off DelayTime  | t <sub>d(off)</sub>                  |  |   | 100    | 160    |       |    |
| Fall Time   | t <sub>f</sub>                       |  |   | 28     | 50     |       |    |
|   |                                      |  |   | 15     | 30     |       |    |
| Drain-Source Body Diode Characteristics                       |                                      |  |   |        |        |       |    |
| Continuous Source-Drain Diode Current                         | I <sub>S</sub>                       | T <sub>C</sub> = 25 °C   |   |        | - 4.6  | A     |    |
| Pulse Diode Forward Current                                   | I <sub>SM</sub>                      |  |   |        | - 50   |       |    |
| Body Diode Voltage  | V <sub>SD</sub>                      | I <sub>S</sub> = - 2 A, V <sub>GS</sub> = 0 V  |   | - 0.75 | - 1.2  | V     |    |
| Body Diode Reverse Recovery Time                              | t <sub>rr</sub>                      | I <sub>F</sub> = - 2 A, dI/dt = 100 A/μs, T <sub>J</sub> = 25 °C   |   | 28     | 45     | ns    |    |
| Body Diode Reverse Recovery Charge                            | Q <sub>rr</sub>                      |  |   | 20     | 40     | nC    |    |
| Reverse Recovery Fall Time                                    | t <sub>a</sub>                       |  |   | 13     |        | ns    |    |
| Reverse Recovery Rise Time                                    | t <sub>b</sub>                       |  |   | 15     |        |       |    |

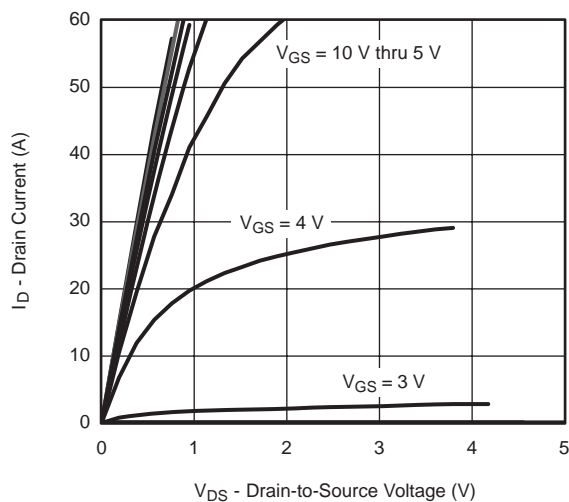
Notes:

a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

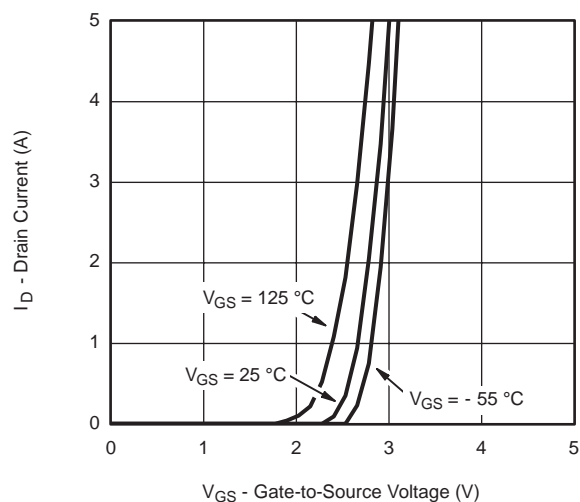
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

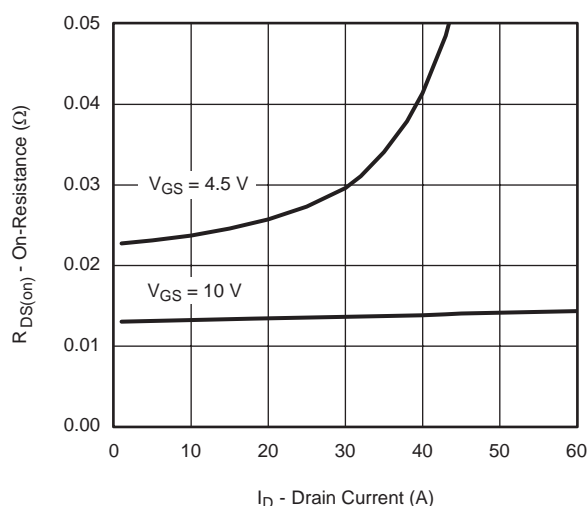
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



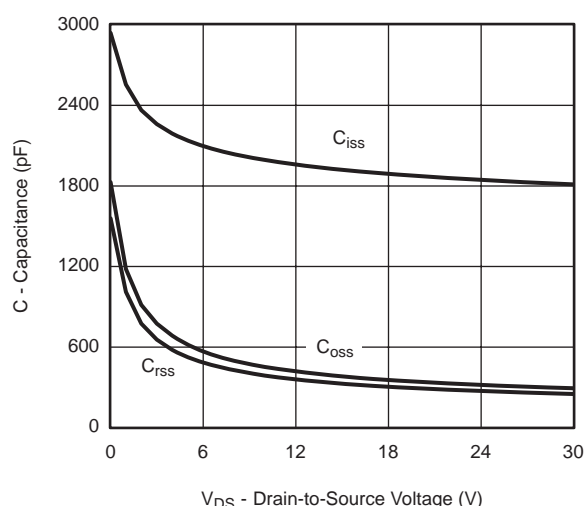
Output Characteristics



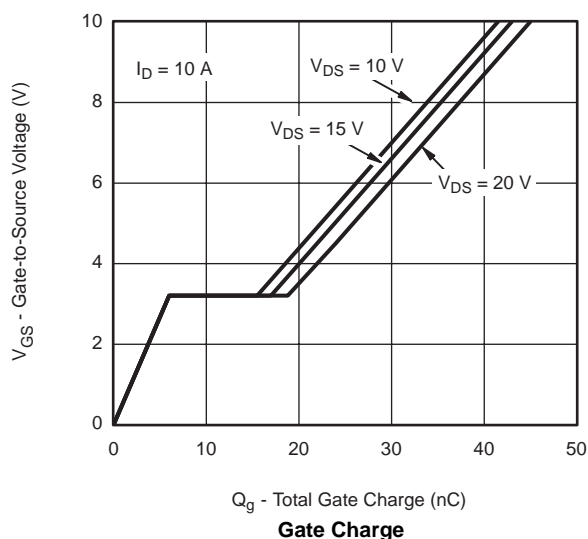
Transfer Characteristics



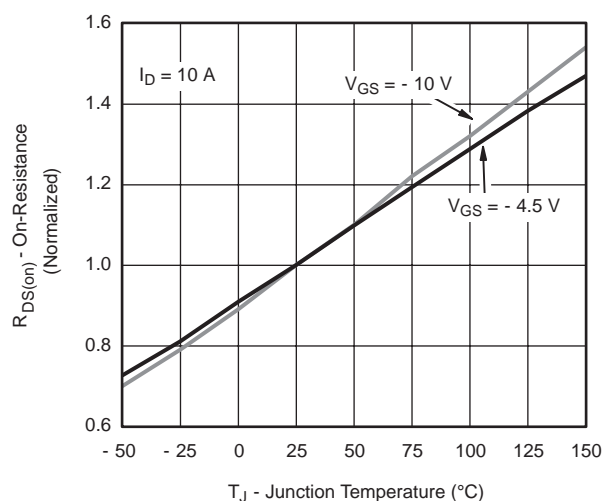
On-Resistance vs. Drain Current



Capacitance

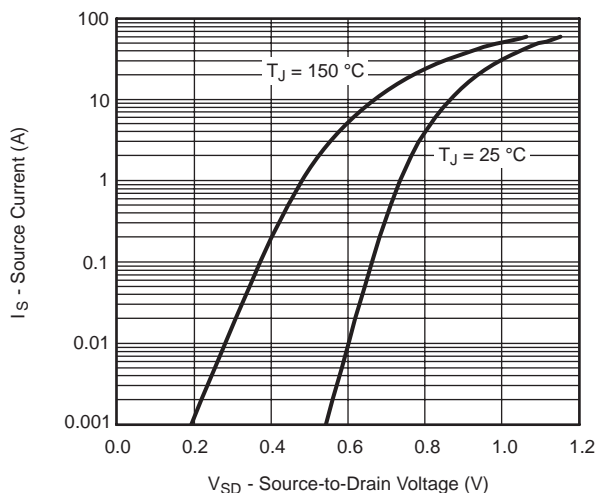


Gate Charge

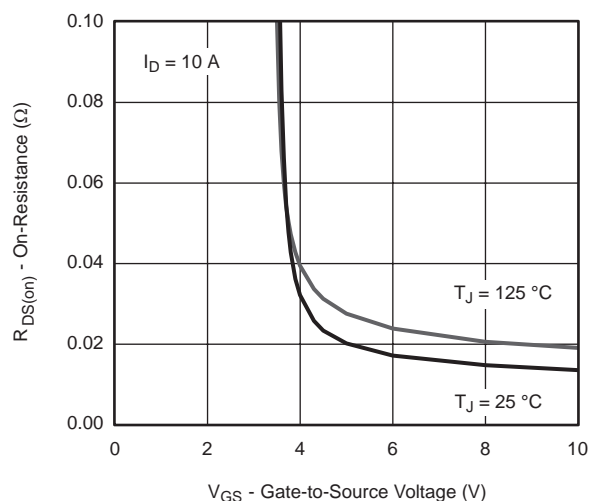


On-Resistance vs. Junction Temperature

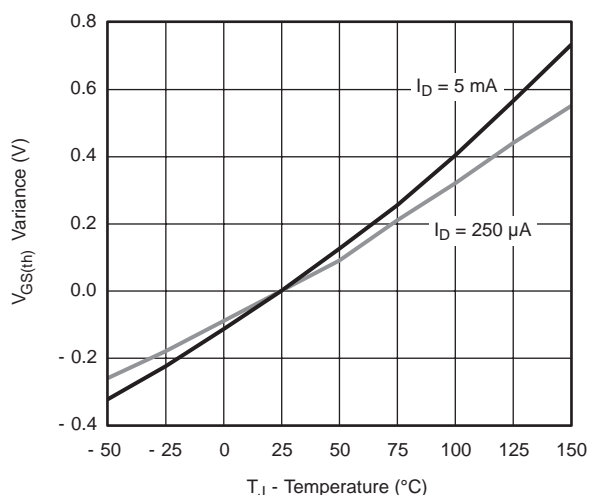
**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



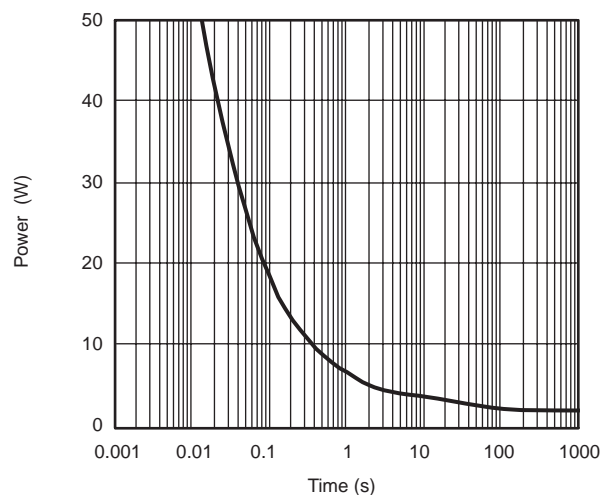
Source-Drain Diode Forward Voltage



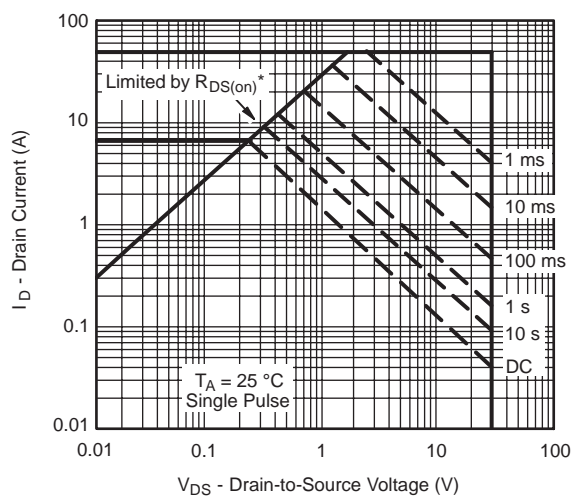
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



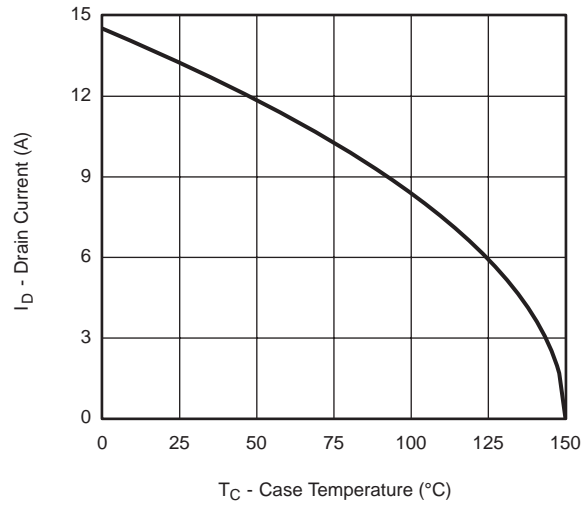
Single Pulse Power, Junction-to-Ambient



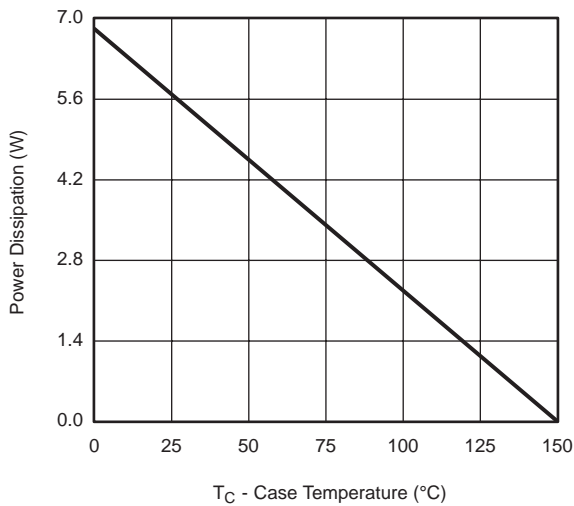
\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area

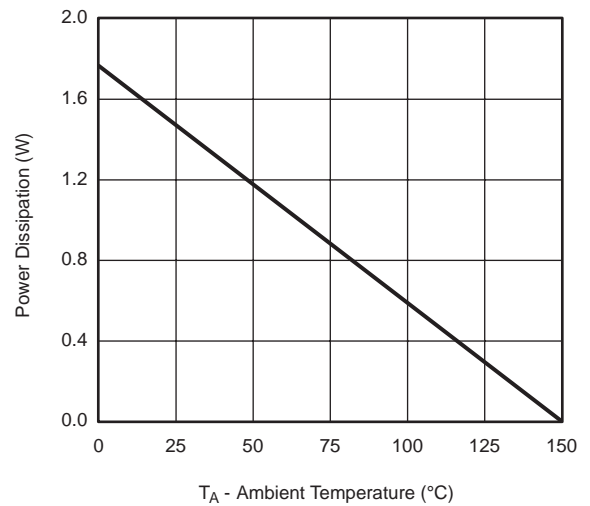
**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



**Current Derating\***



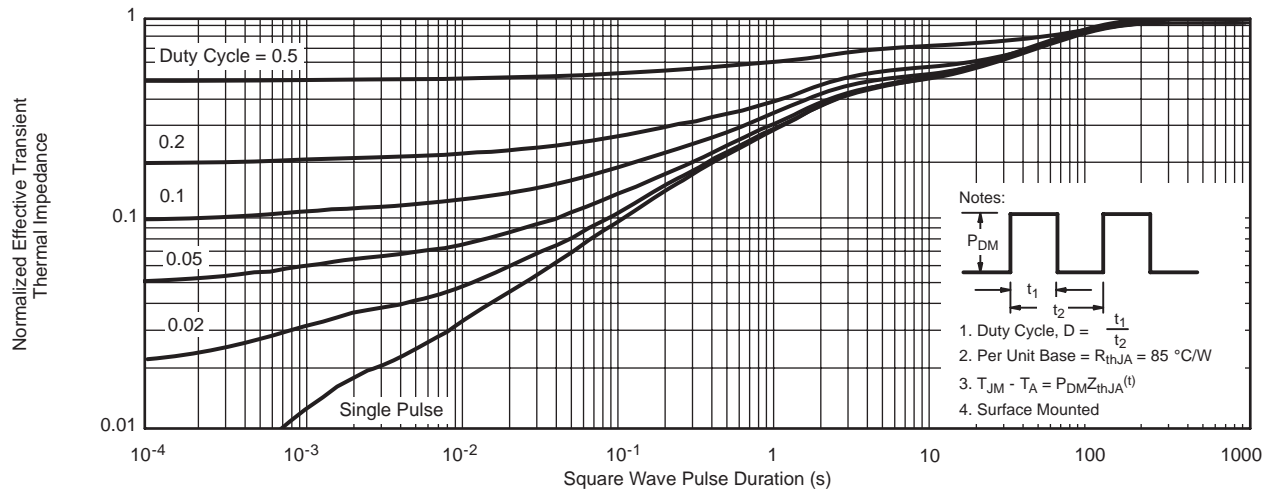
**Power, Junction-to-Foot**



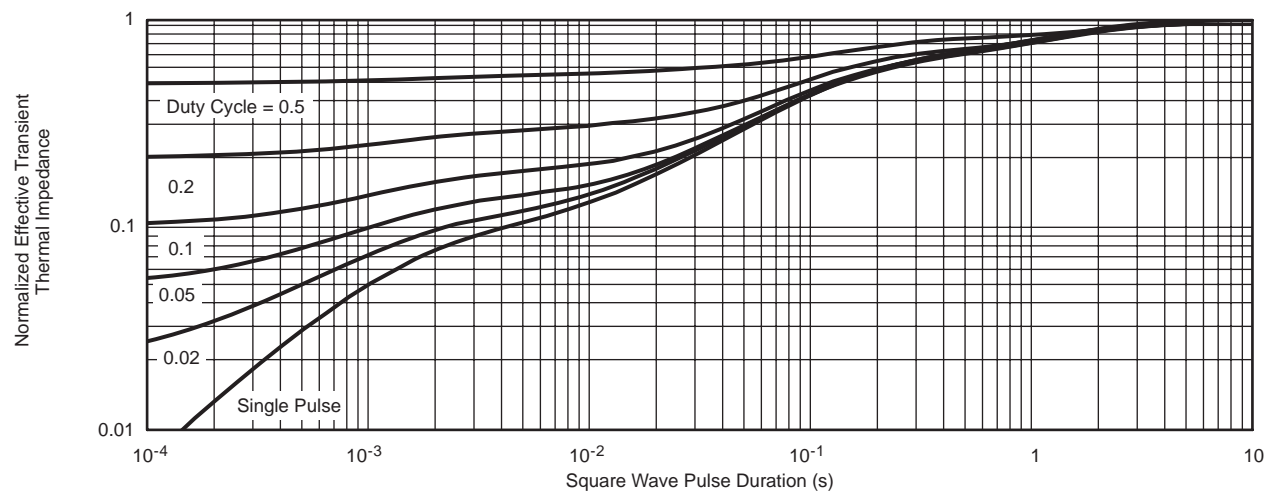
**Power Derating, Junction-to-Ambient**

\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



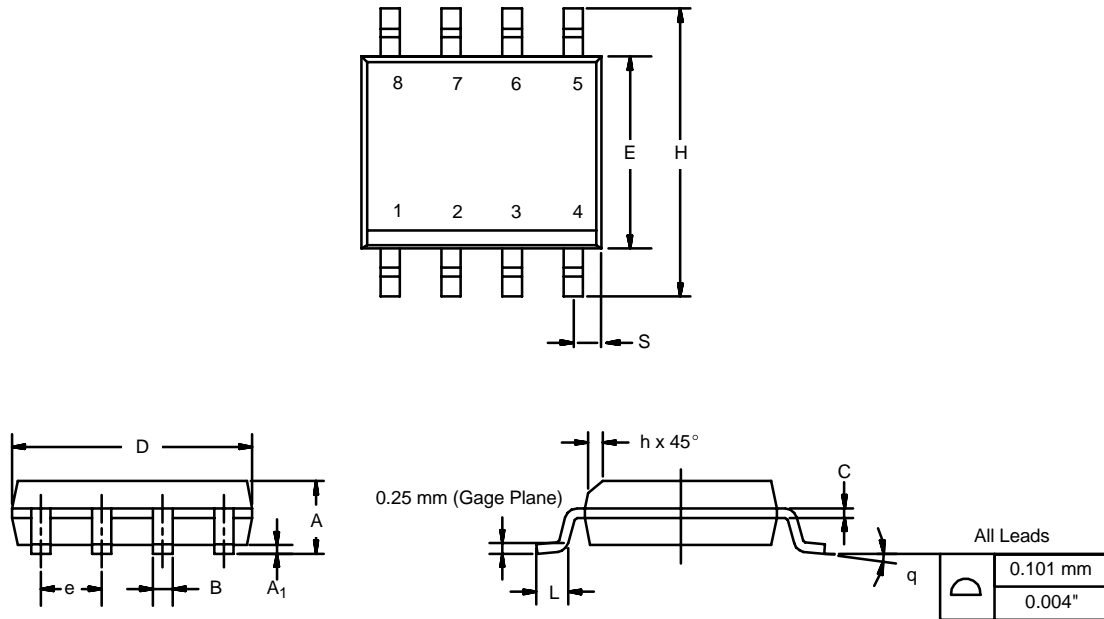
**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**Normalized Thermal Transient Impedance, Junction-to-Foot**

## SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012



| DIM            | MILLIMETERS |      | INCHES    |       |
|----------------|-------------|------|-----------|-------|
|                | Min         | Max  | Min       | Max   |
| A              | 1.35        | 1.75 | 0.053     | 0.069 |
| A <sub>1</sub> | 0.10        | 0.20 | 0.004     | 0.008 |
| B              | 0.35        | 0.51 | 0.014     | 0.020 |
| C              | 0.19        | 0.25 | 0.0075    | 0.010 |
| D              | 4.80        | 5.00 | 0.189     | 0.196 |
| E              | 3.80        | 4.00 | 0.150     | 0.157 |
| e              | 1.27 BSC    |      | 0.050 BSC |       |
| H              | 5.80        | 6.20 | 0.228     | 0.244 |
| h              | 0.25        | 0.50 | 0.010     | 0.020 |
| L              | 0.50        | 0.93 | 0.020     | 0.037 |
| q              | 0°          | 8°   | 0°        | 8°    |
| S              | 0.44        | 0.64 | 0.018     | 0.026 |

ECN: C-06527-Rev. I, 11-Sep-06  
DWG: 5498

## RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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